

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	696	(vary or variation or change\$3 or alter\$3) with ("wt %" or "%" or percent\$3 or concentration) with (((peroxide or H2O2 or "H.sub.2O.sub.2") same (NH4OH or ammonia or "ammonium hydroxide" or "NH.sub.4OH") same (HF of hydrofluoric or "hydrogen fluoride") same (phosphoric or H3PO4 or "H.sub.3PO.sub.4"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 11:18			
2	BRS	L2	0	(vary or variation or change\$3 or alter\$3) with ("wt %" or "%" or percent\$3 or concentration) with (((peroxide or H2O2 or "H.sub.2O.sub.2") same (NH4OH or ammonia or "ammonium hydroxide" or "NH.sub.4OH") same (HF of hydrofluoric or "hydrogen fluoride") same (phosphoric or H3PO4 or "H.sub.3PO.sub.4")) same etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 11:19			
3	BRS	L3	5	("wt %" or "%" or percent\$3 or concentration) with (((peroxide or H2O2 or "H.sub.2O.sub.2") same (NH4OH or ammonia or "ammonium hydroxide" or "NH.sub.4OH") same (HF of hydrofluoric or "hydrogen fluoride") same (phosphoric or H3PO4 or "H.sub.3PO.sub.4")) same etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 11:55			
4	BRS	L4	0	("wt %" or "%" or percent\$3 or concentration) with (((peroxide or H2O2 or "H.sub.2O.sub.2") same (NH4OH or ammonia or "ammonium hydroxide" or "NH.sub.4OH") same (HF of hydrofluoric or "hydrogen fluoride") same (phosphoric or H3PO4 or "H.sub.3PO.sub.4")) same etch\$3 same temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 11:55			
5	BRS	L5	427	etch\$3 same (("wt %" or "%") with (phosphoric or H3PO4 or "H.sub.3PO.sub.4"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 11:56			
6	BRS	L6	16	etch\$3 same (("wt %" or "%") with (phosphoric or H3PO4 or "H.sub.3PO.sub.4")) with (nitride or SiN or Si3N4 or "Si.sub.3N.sub.4")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 12:16			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
7	BRS	L7	4	etch\$3 same (("wt %" or "%") with ((phosphoric or H3PO4 or "H.sub.3PO.sub.4") and (HF or hydrofluoric or "hydrogen fluoride"))) with (nitride or SiN or Si3N4 or "Si.sub.3N.sub.4"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 12:53			
8	BRS	L8	3875	((fill\$3 or deposit\$3) with polysilicon) same (cmp or polish\$3 or planariz\$5) same (SAC or (self adj align\$4) or "contact hole" or hole or open\$3 or node or nodal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 12:57			
9	BRS	L9	2489	((fill\$3 or deposit\$3) with polysilicon) with (SAC or (self adj align\$4) or "contact hole" or hole or open\$3 or node or nodal)) same (cmp or polish\$3 or planariz\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 12:58			
10	BRS	L10	1771	((fill\$3 or deposit\$3) with polysilicon) with (SAC or (self adj align\$4) or "contact hole" or hole or open\$3 or node or nodal)) same (cmp or polish\$3 or planariz\$5) same etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 13:00			
11	BRS	L11	1088	10 and @pd<="20031114"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 13:02			
12	BRS	L12	455	((fill\$3 or deposit\$3) with polysilicon) with (SAC or (self adj align\$4) or "contact hole" or hole or open\$3 or node or nodal)) same (cmp or polish\$3 or planariz\$5) same etch\$3 same (source and drain)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 13:48			
13	BRS	L13	291	12 and @pd<="20031114"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 13:51			
14	BRS	L14	1598	((fill\$3 or deposit\$3) with polysilicon) with (SAC or (self adj align\$4) or "contact hole" or hole or open\$3 or node or nodal)) same (cmp or ((chemical\$2 adj mechanical\$2) adj (planariz\$5 or polish\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 13:48			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
15	BRS	L15	284	((fill\$3 or deposit\$3) with polysilicon) with (SAC or (self adj align\$4) or "contact hole" or hole or open\$3 or node or nodal)) same (cmp or ((chemical\$2 adj mechanical\$2) adj (planariz\$5 or polish\$3))) same etch\$3 same (source and drain)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 13:48			
16	BRS	L16	167	15 and @pd<="20031114"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2007/03/12 13:51			